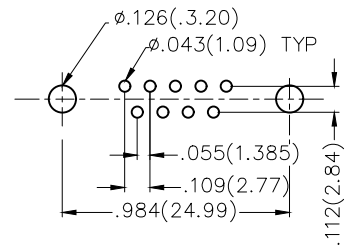
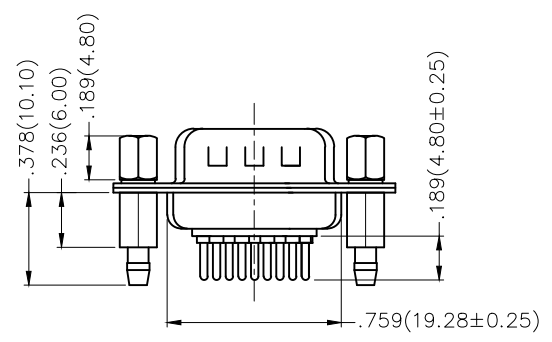
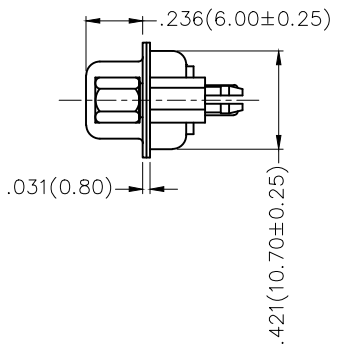
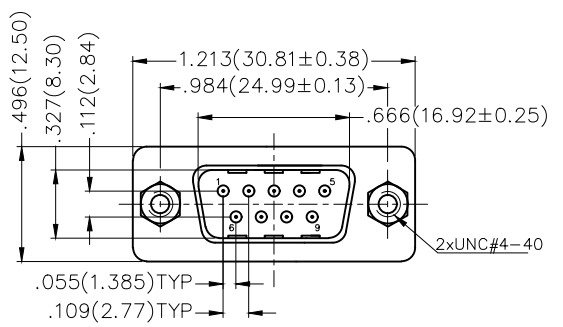


REV	LOCATIONS	DESCRIPTION	DATE	REVISED	APPD



Recommended P.C.Board Layout

### Ordering Information

FDM 09 04 — MO D S 1 XX XX X  
 1 2 3 4 5 6 7 8 9 10

1	Category	2	Circuits	3	Distinction No.	4	Type	5	Assembly Layout
	FDM—Machined pin D—SUB connector		09		04		MO—Male		D—DIP
6	Entry Angle	7	Plating	8	Thickness of Plating	9	Color—Resin	10	Packaging
	S—180° Vertical		1—Gold Plated		01—1µ" 03—3µ" Custom plate available		W1—White K6—Black		K—Tray L—Tube

**Materials And Finish**  
 Shell: Spcc Material, Front Nickel Plated 80µ" Min  
 Back Shell: SPCC, Tin Plated 100µ" Min  
 Insulator: Glass Filled Thermoplastic, UL 94V-0  
 Contact Material: Brass /Gold Plated  
**Electrical Characteristic**  
 Current Rating: 7.5A  
 Voltage Rating: 300V  
 Contact Resistance: 5mΩ Max  
 Dielectric Withstanding Voltage :1000V AC r.m.s  
 Insulation Resistance: 5000 MΩ Min.  
 Temperature Range—Operating: -55°C ~ +105°C

 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	 Leader Of Industry
	X.±.012(0.30)	X.±5'	FRANK	23/JUL/13	FDM0904—MODS1XXXXX	FDM0904	
DESIGN UNITS Inch (metric)	X.X±.008(0.20)	.X'±2'	CHECKED BY	DATE	TITLE		REV 0
SCALE	X.XX±.006(0.15)	.XX'±1'	CHERRY	23/JUL/13	Machined pin D—SUB connector 180° Vertical Male		SHEET NO. 1/1
SIZE	X.XXX±.004(0.10)	.XXX'±0.5'	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
5:1	A4		JACOB	23/JUL/13			